

## **ATS-HK379-R0**

The ATS-HK379-R0 is an optional backing plate designed for connecting CPUs and other high-powered processors (including GPUs, Al processors, and FPGAs) that fit sockets other than the Intel™ LGA2011 square and LGA2066 (Socket R) to the Ultra-Cool family of high-performance passive and active thermal solutions, inlcuding dual-FLOW™ and quadFLOW™.

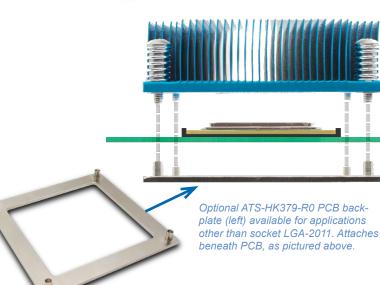
The ATS-HK379-R0 also comes with an unattached die-cut Formex GK-10 insulator to provide electrical insulation between the board and the backing plate. It is intended for use with 1.57-mm thick PCB. For applications with a different thickness PCB, contact ATS.

## **Features & Benefits**

- « Dimensions (L x W): 96 x 96 mm (Inner Dimension: 70 x 70 mm)
- « Material: Steel (comes with unattached Formex GK-10 insulator)
- « Required mounting holes in PCB: 7.60 +0.35/-0.00
- « Attaches beneath the PCB for even pressure across the board to prevent cracking or other damage

- « Backing Plate designed for use with 1.57-mm thick PCB
- « Mechanical attachment is PEM, screws and spring; For other types of attachments contact ATS
- « Final mounting pressure dependent on component height and contact area, contact ATS for details





## **Product Details**

Part Number	Material	Length (mm)	Width (mm)	Hole to Hole (mm)	Standoff Height (mm)	Inner Length (mm)	Inner Width (mm)
ATS-HK379-R0	Al	96	96	80	6.0	70	70

## **NOTES:**

- 1. Backing Plate designed for use when LGA2011 Socket not present
- 2. Backing Plate designed for use with 1.57-mm thick PCB
- 3. RoHS-6 and REACH compliant



